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Patent

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Customer No. 31561
Docket No. 10665-US-PA
Application No.: 10/605,305

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Ho et al.
Application No. : 10/605,305
Filed : 2003/9/22
For : BUMP PROCESS FOR FLIP CHIP PACKAGE
Examiner : GEYER, SCOTT B
Art Unit : 2829

INFORMATION DISCLOSURE STATEMENT

002-1-703-872-9306

(Via fax: 56 pages, followed by confirmation copy via courier)

ASSISTANT COMMISSIONER FOR PATENTS
Arlington, VA22202

Enclosed is a PTO Form 1449 listing 1 reference(s), copy of which is attached. Applicant submits the reference(s) in compliance with his duty of disclosure pursuant to 37 CFR § 1.56 and 1.97. The Examiner is requested to make the citation(s) of official record.

The IDS is being submitted after the mailing date of a notice of allowance. Attached herewith please find a copy of Applicants' statement under 37 CFR § 1.97 (e). Please charge the payment in the amount of US\$180.00 to account No. 50-2620 (Order No.: 10665-US-PA) to cover the fee set forth in 37 CFR 1.17(p).

The submission of the reference(s) should not be interpreted as admitting them as prior art.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property OfficeDate: August 20, 2004By: Belinda Lee

Belinda Lee

Registration No.: 46,863

Please send future correspondence to:

7F. -1, No. 100, Roosevelt Rd., Sec. 2, Taipei 100, Taiwan, R.O.C.

Tel: 886-2-2369 2800 Fax: 886-2-2369 7233 / 886-2-2369 7234

E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw

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FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICATION	ATTY. DOCKET NO.: 10665-US-PA	APPLICATION NO.: 10/605,305
	APPLICANT: Ho et al.	
	FILING DATE: 2003/9/22	GROUP 2829

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
	09/844,224	2001/4/27	Hsue et al.			

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
L.W.	516142	2003/1/1	Taiwan, R. O. C.			2001/12/17

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

EXAMINER	DATE CONSIDERED
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EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED. INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.

Customer No.: 31561
Application No.: 10/605,305
Docket No.: 10665-US-PA

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Kwun-Yao Ho et al.,
Application No. : 10/605,305
Filed : September 22, 2003
Title : BUMP PROCESS FOR FILP CHIP PACKAGE

Grp./Div. : 2829
Examiner : Geyer, Scott B

Docket No. : 10665-US-PA

STATEMENT UNDER C.F.R. 1.97(e)

I, hereby state that no item of information contained in the enclosed Information Disclosed Statement (IDS) was cited in a communication from a foreign patent office in a counterpart foreign application, and, to my knowledge after making reasonable inquiry, no item of information contained in the IDS was known to any individual designated in 37 CFR 1.56(c) (those individuals include: (a) each inventor, (b) each attorney/agent who prepares or prosecutes the application, and (c) every other person who is substantially involved in the preparation or prosecution of the application and who is associated with the inventor, with the assignee or with anyone to whom there is an obligation to assign the application) more than three months prior to the filing of the IDS.

I hereby state that all items of information contained in the IDS, TW 516142; US 09/844224, were found on June 23, 2004 in a prior art search.

Date Aug. 20, 2004

By Wei-Chi Yeh
Patent Engineer
Legal Division
VIA Technologies, Inc.